PCN Number:	20190517000.1	**PCN Date:**	May 20, 2019
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Aug 20, 2019	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Material	Current	Proposed
Mold compound	31252002-0	31125011-0

Reason for Change:

Continuity of supply.

Mold compound supplier (Shinetsu) decided to end of life part no. 31252002-0 mold compound

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

None

Product Affected:

LM3S1138-IBZ50-A2T	LM3S1968-IBZ50-A2T	LM3S6911-IBZ50-A2	LM3S8530-IBZ50-A2
LM3S1751-IBZ50-A2	LM3S2965-IBZ50-A2	LM3S6911-IBZ50-A2T	LM3S8530-IBZ50-A2T
LM3S1911-IBZ50-A2T	LM3S6432-IBZ50-A2	LM3S6915-IBZ50-A2	LM3S8938-IBZ50-A2
LM3S1918-IBZ50-A2	LM3S6432-IBZ50-A2T	LM3S6918-IBZ50-A2	LM3S8962-IBZ50-A2
LM3S1968-IBZ50-A2	LM3S6611-IBZ50-A2	LM3S6965-IBZ50-A2	

Qualification Report

Approve Date 14-May-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM3S1XXX-IBZ50-A2T (SINGLE DIE)	Qual Device: LMS6XXX-IBZ50-A2 (STACKED DIE)
PC	Preconditioning	MSL3/260C	1/77/0	1/154/0
TC	Temperature cycling - 55C/125C	700 cycles	1/66/0	1/71/0
UHAST	Unbiased HAST	110C/85%RH/17.7 psis (264 Hours)	-	1/72/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass

- Device LMS6XXX-IBZ50-A2 (STACKED DIE) contains multiple dies.
- Preconditioning was performed for Unbiased HAST, Temperature Cycle
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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